

E4MS047120U2

Silicon Carbide Power MOSFET
Switching Optimized 1200V 47mΩ Automotive
N-Channel Enhancement Mode

Features

- Industry compatible drive voltage 15V...18V/-5V...0V
- Soft body diode with low V_{DSS} overshoot and ringing
- Low $R_{DS(on)}$ at high operating temperatures
- Improved device capacitances ratio (C_{iss}/C_{rss})
- High transient voltage robustness with improved lifetime
- Halogen free, RoHS compliant
- Automotive Qualified (AEC-Q101) and PPAP Capable

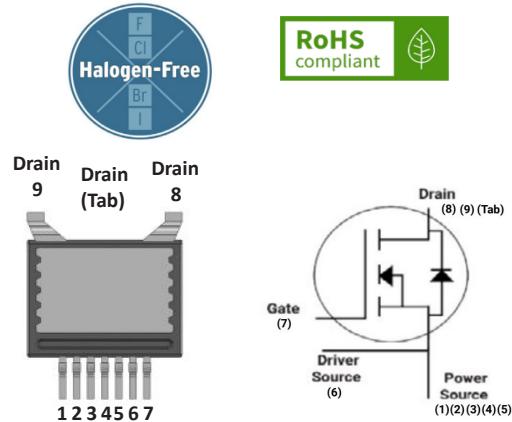
Benefits

- Higher efficiency with lower switching losses and EMI
- Faster switching operation enabling high power density
- Enables system level price performance optimization
- Reduction in system level cooling requirements

Typical Applications

- Motor Control
- EV On Board Battery Chargers (OBC)
- Automotive DC/DC Converters for EV/HEV

Package



Orderable Part number	Package type	Marking
E4MS047120U2-TR	TO-263-7XL	E4MS047120U2

Key Parameters

Parameter	Symbol	Min.	Typ.	Max	Unit	Conditions	Note
Drain - Source Voltage	V_{DS}			1200	V		
Maximum Gate - Source Voltage	$V_{GS(max)}$	-10		+23			
DC Continuous Drain Current	I_D			48	A	$V_{GS} = 18 \text{ V}, T_c = 25 \text{ }^\circ\text{C}, T_j \leq 175 \text{ }^\circ\text{C}$	Note 1
				35		$V_{GS} = 18 \text{ V}, T_c = 100 \text{ }^\circ\text{C}, T_j \leq 175 \text{ }^\circ\text{C}$	
Pulsed Drain Current	I_{DM}			147		t_{pmax} limited by $T_{j(max)}$ $V_{GS} = 18 \text{ V}, T_c = 25 \text{ }^\circ\text{C}$	
Power Dissipation	P_D			217	W	$T_c = 25 \text{ }^\circ\text{C}, T_j = 175 \text{ }^\circ\text{C}$	Note 2
Operating Junction and Storage Temperature	T_j, T_{stg}	-55		+175	${}^\circ\text{C}$		
Solder Temperature	T_L			260			

Note (1): Current limit calculated by $I_{D(max)} = \sqrt{(P_D / R_{DS(typ)})(T_{j(max)} / I_{D(max)})}$

Note (2): $P_D = (T_j - T_c) / R_{th(jC,max)}$


Electrical Characteristics (T_c = 25°C unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions	Note
V _{(BR)DSS}	Drain-Source Breakdown Voltage	1200			V	V _{GS} = 0 V, I _D = 100 μA	
V _{GS(th)}	Gate Threshold Voltage	2	2.6	3.9	V	V _{DS} = V _{GS} , I _D = 5.8 mA	Fig. 11
			2.0		V	V _{DS} = V _{GS} , I _D = 5.8 mA, T _J = 175°C	
I _{DSS}	Zero Gate Voltage Drain Current		1	50	μA	V _{DS} = 1200 V, V _{GS} = 0 V	
I _{GSs}	Gate-Source Leakage Current		10	250	nA	V _{GS} = 18 V, V _{DS} = 0 V	
V _{GS(op)}	Recommended Turn on Gate-Source Voltage	+15...+18			V		Refer to PRD-09634
	Recommended Turn off Gate-Source Voltage	-5...0					
R _{DS(on)}	Drain-Source On-State Resistance		47	61	mΩ	V _{GS} = 18 V, I _D = 21 A	Fig. 4, 5, 6
			89			V _{GS} = 18 V, I _D = 21 A, T _J = 175°C	
			53			V _{GS} = 15 V, I _D = 21 A	
g _{fs}	Transconductance		15		S	V _{DS} = 20 V, I _D = 21 A, T _J = 25°C	Fig. 7
			15			V _{DS} = 20 V, I _D = 21 A, T _J = 175°C	
R _{DS(on)Tempco}	On resistance temperature coefficient		1.88			V _{GS} = 18 V, I _D = 21 A	Note 3
C _{iss}	Input Capacitance		1640		pF	V _{GS} = 0 V, V _{DS} = 1000 V f = 100 kHz V _{AC} = 25 mV	Fig. 17, 18
C _{oss}	Output Capacitance		57				
C _{rss}	Reverse Transfer Capacitance		3				
C _{iss/C_{rss}}	Capacitance Ratio		630				Note 4
E _{oss}	C _{oss} Stored Energy		37		μJ		Fig. 16
C _{o(er)}	Effective Output Capacitance (Energy Related)		83		pF	V _{GS} = 0V, V _{DS} = 0...800V	
C _{o(tr)}	Effective Output Capacitance (Time Related)		136				
E _{on}	Turn-On Switching Energy (Body Diode FWD) T _J =25C T _J =175C		216		μJ	V _{DS} = 800 V, V _{GS} = -4 V/18 V, I _D = 21 A, R _{G(ext)} = 2 Ω, L _o = 25 nH	Fig. 26, 29, 31
			242				
E _{off}	Turn-Off Switching Energy (Body Diode FWD) T _J =25C T _J =175C		28				Fig. 26, 29, 32
			30				
t _{d(on)}	Turn-On Delay Time		10		ns	V _{DD} = 800 V, V _{GS} = -4 V/18 V I _D = 21 A, R _{G(ext)} = 2 Ω, Timing relative to V _{DS} Inductive load	Fig. 27, 28
t _r	Rise Time		2				
t _{d(off)}	Turn-Off Delay Time		23				
t _f	Fall Time		4				
R _{G(int)}	Internal Gate Resistance		2.8		Ω	f = 1 MHz	
Q _{gs}	Gate to Source Charge		18		nC	V _{DS} = 800 V, V _{GS} = -4 V/18 V I _D = 21 A, T _J = 25°C Per IEC60747-8-4 pg 21	Fig. 12
Q _{gd}	Gate to Drain Charge		18				
Q _g	Total Gate Charge		68				

Note (3): R_{DS(on)Tempco} refers to R_{DS(on)} at 175°C / R_{DS(on)} at 25°C, E4MS 1200V product family value

Note (4): Capacitance ratio is a FOM for Partial turn-on immunity PRD-09633, E4MS 1200V product family value

Co(er), a lumped capacitance that gives the same stored energy as Coss while Vds is rising from 0 to 800V

Co(tr), a lumped capacitance that gives the same charging time as Coss while Vds is rising from 0 to 800V



Reverse Diode Characteristics ($T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
V_{SD}	Diode Forward Voltage	5.2		V	$V_{GS} = -4\text{ V}$, $I_{SD} = 10.5\text{ A}$, $T_j = 25^\circ\text{C}$	Fig. 8, 9, 10
		4.6		V	$V_{GS} = -4\text{ V}$, $I_{SD} = 10.5\text{ A}$, $T_j = 175^\circ\text{C}$	
I_s	Continuous Diode Forward Current		33	A	$V_{GS} = -4\text{ V}$, $T_c = 25^\circ\text{C}$	
I_{SM}	Diode Pulse Current		147	A	$V_{GS} = -4\text{ V}$, pulse width t_p limited by T_{jmax}	
t_{rr}	Reverse Recovery Time	12		ns	$V_{GS} = -4\text{ V}$, $I_s = 21\text{ A}$, $V_{SD} = 800\text{V}$ $T_j = 175^\circ\text{C}$, $dI/dt = 12.7\text{ A/ns}$	
Q_{rr}	Reverse Recovery Charge	449		nC		
I_{RRM}	Peak Reverse Recovery current	65		A		
E_{RR}	Reverse recovery Energy				$V_{DS} = 800\text{ V}$, $I_D = 21\text{ A}$,	
	$T_j = 25^\circ\text{C}$	61		μJ	$V_{GS} = -4\text{ V}/18\text{V}$, $R_{G(on)} = 2\Omega$, $L\sigma = 25\text{nH}$	
$T_j = 175^\circ\text{C}$		140				

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	0.53	0.69	$^\circ\text{C/W}$		

Typical Performance

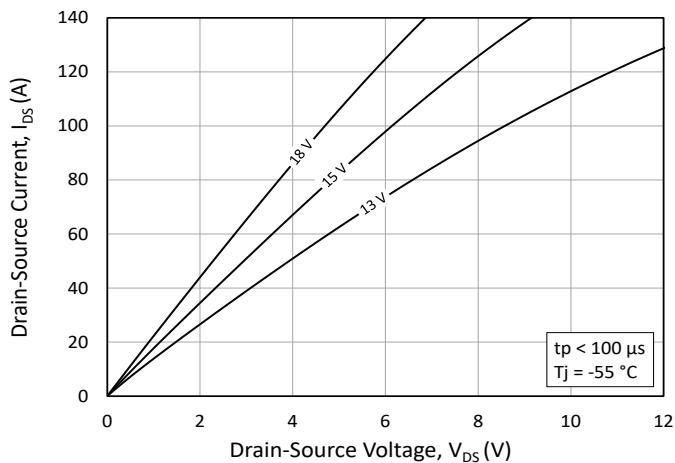
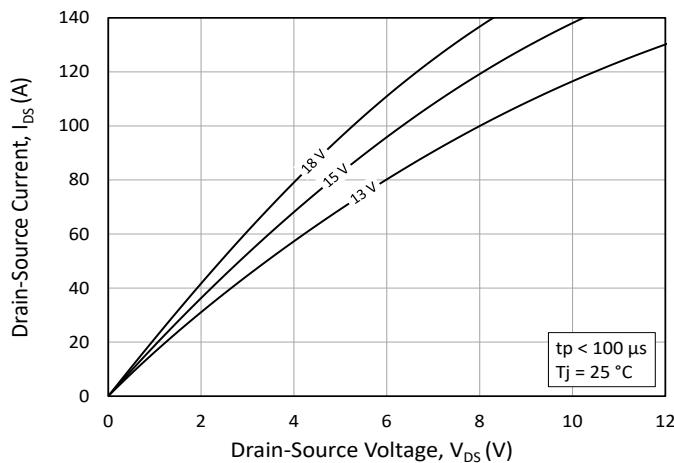
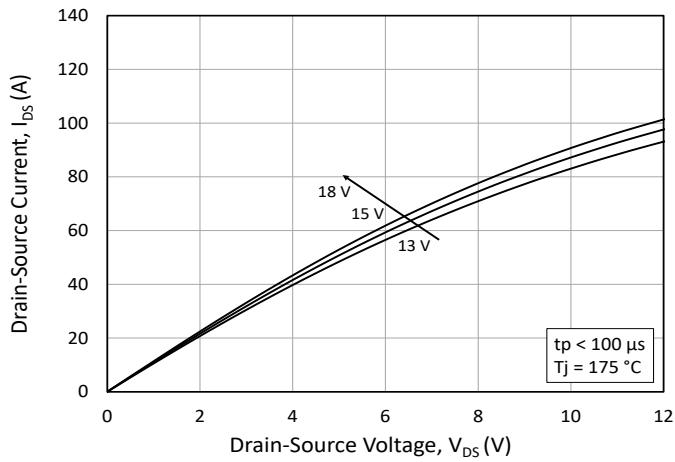
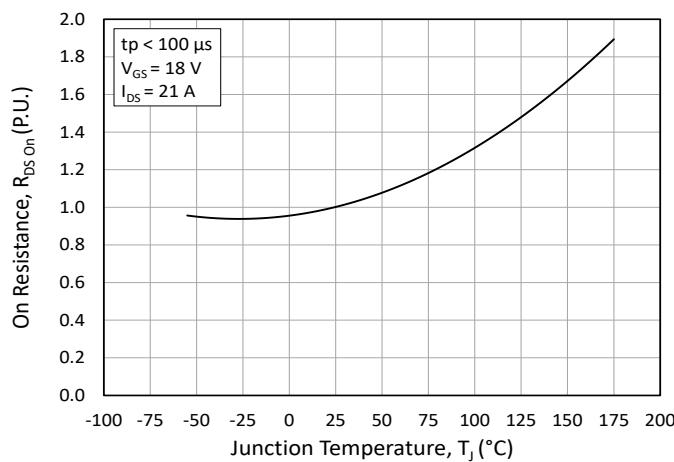
Figure 1. Output Characteristics $T_j = -55^\circ\text{C}$ Figure 2. Output Characteristics $T_j = 25^\circ\text{C}$ Figure 3. Output Characteristics $T_j = 175^\circ\text{C}$ 

Figure 4. Normalized On-Resistance vs. Temperature

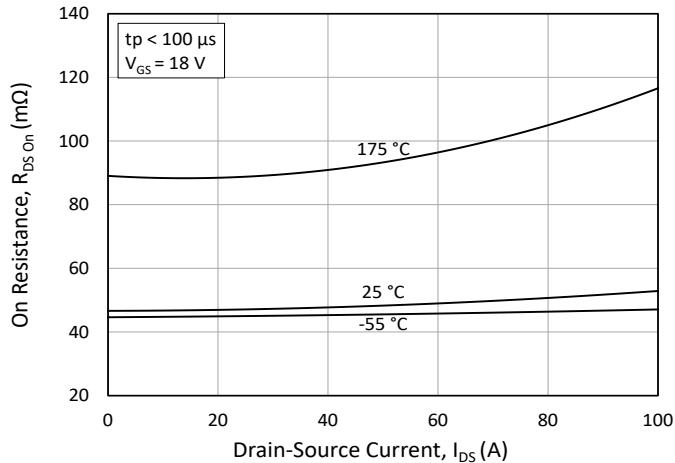


Figure 5. On-Resistance vs. Drain Current For Various Temperatures

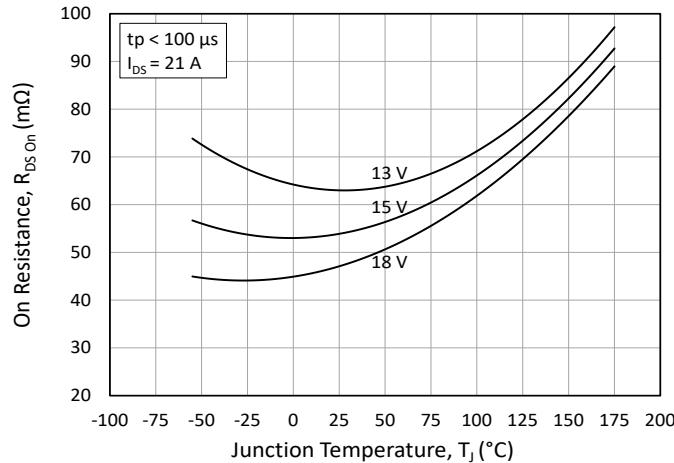
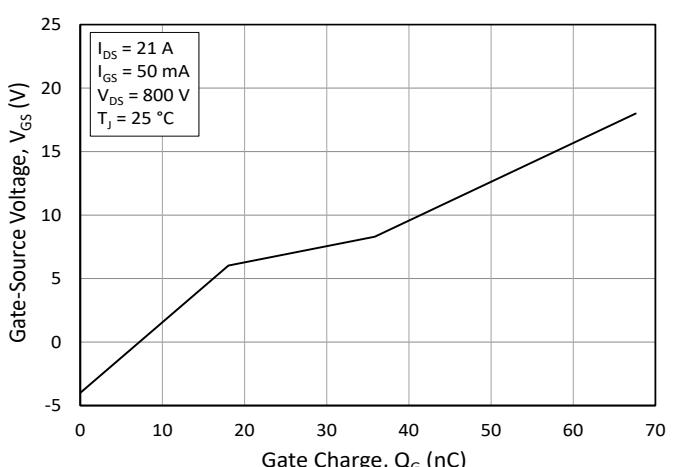
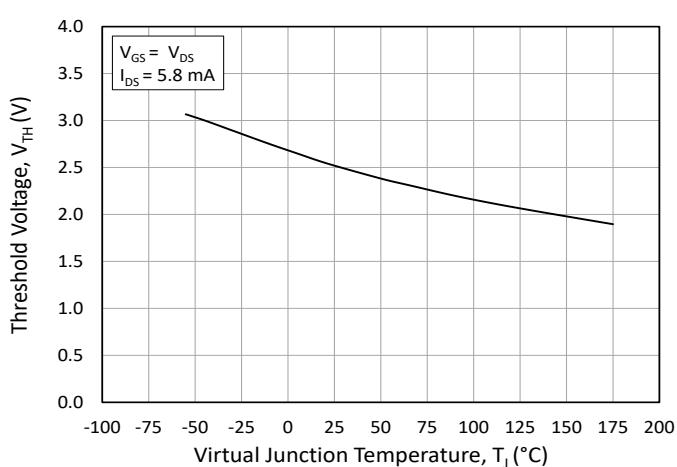
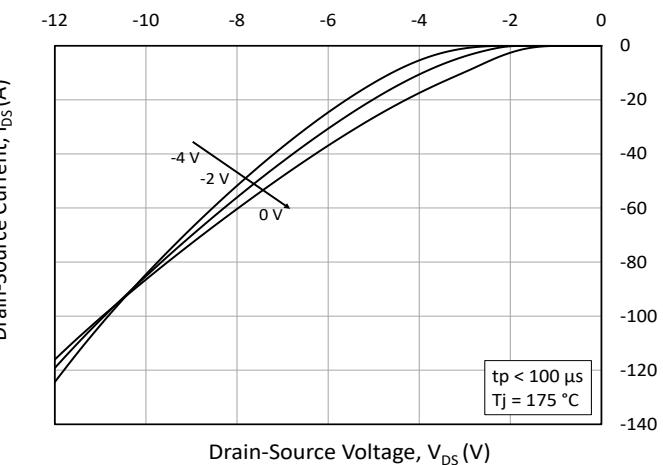
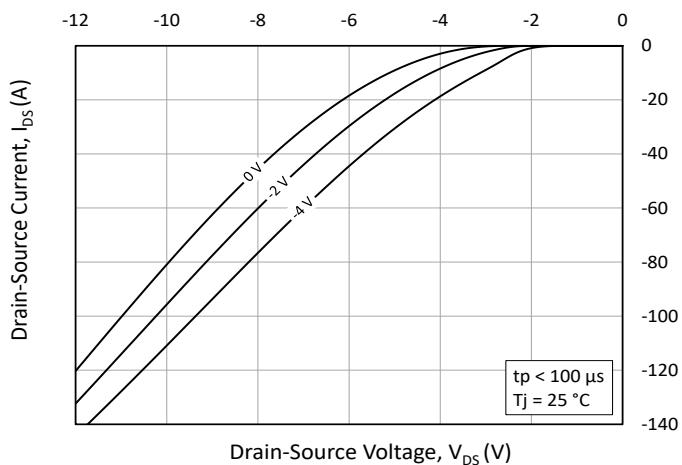
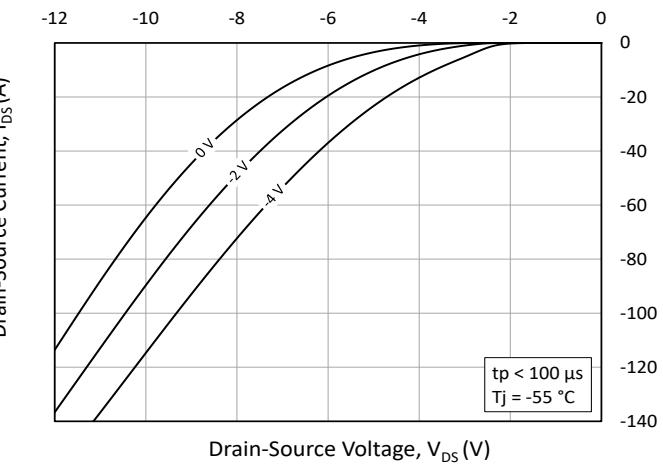
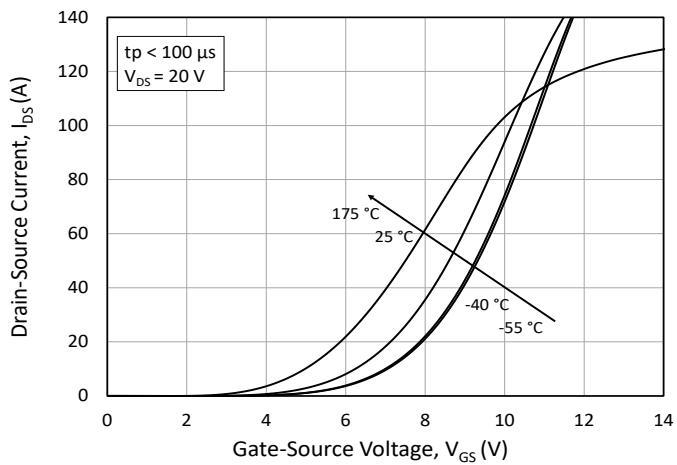


Figure 6. On-Resistance vs. Temperature For Various Gate Voltage

Typical Performance



Typical Performance

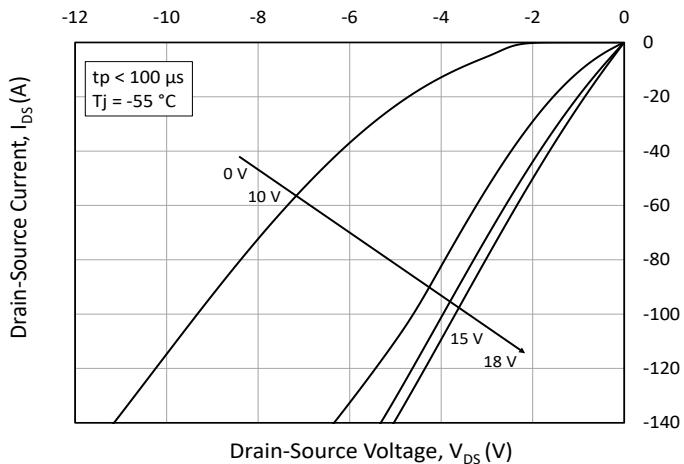
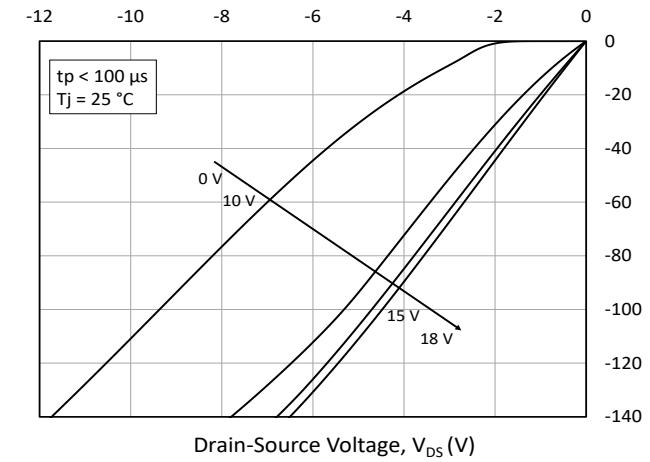
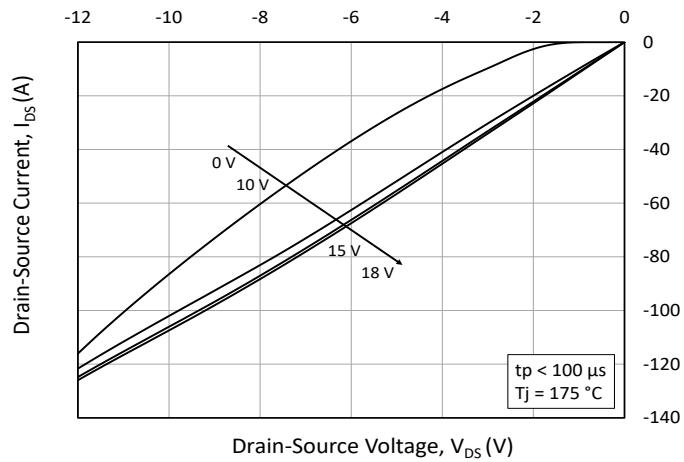
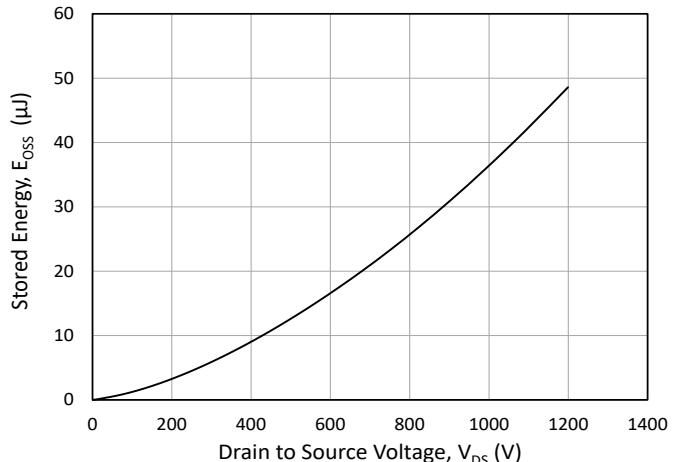
Figure 13. 3rd Quadrant Characteristic at -55°C Figure 14. 3rd Quadrant Characteristic at 25°C Figure 15. 3rd Quadrant Characteristic at 175°C 

Figure 16. Output Capacitor Stored Energy

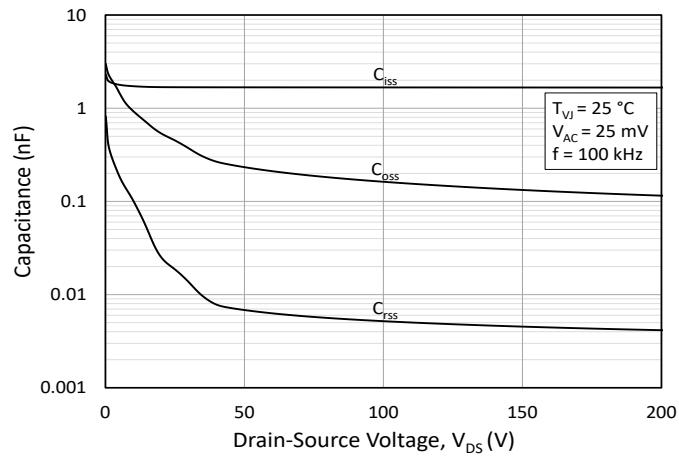


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200 V)

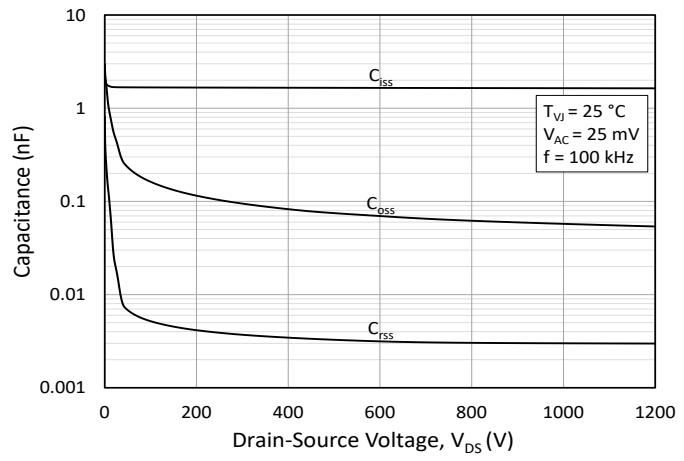


Figure 18. Capacitances vs. Drain-Source Voltage (0 - 1200 V)

Typical Performance

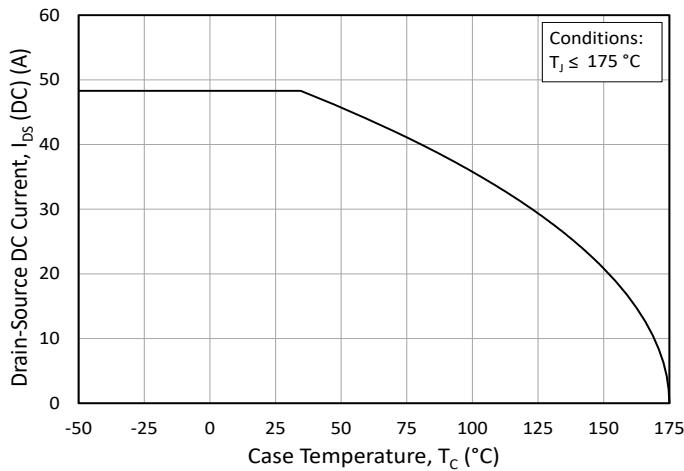


Figure 19. Continuous Drain Current Derating vs. Case Temperature

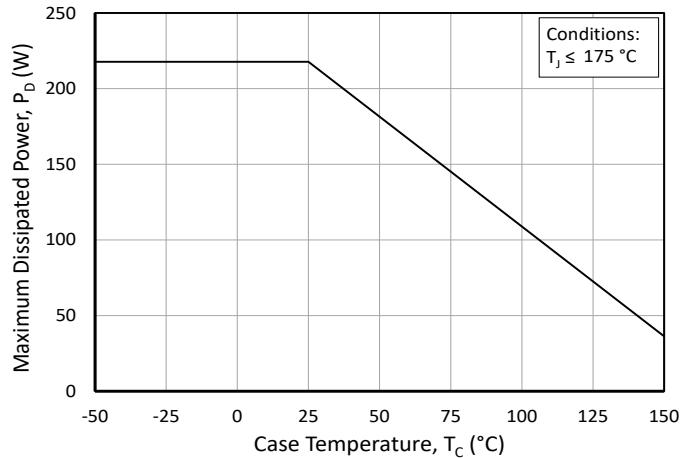


Figure 20. Maximum Power Dissipation Derating vs. Case Temperature

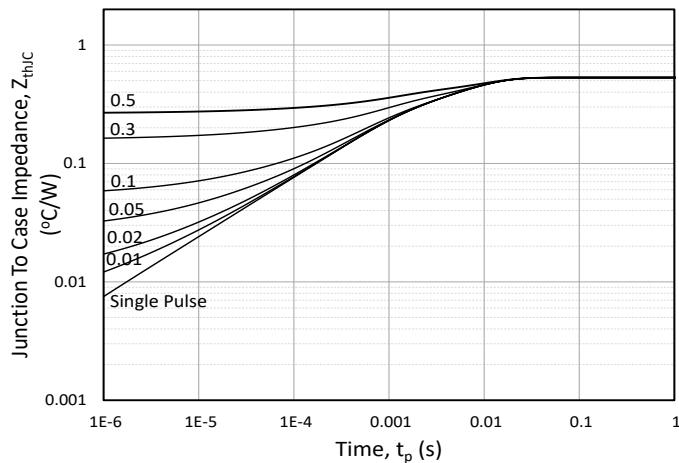


Figure 21. Transient Thermal Impedance (Junction - Case)

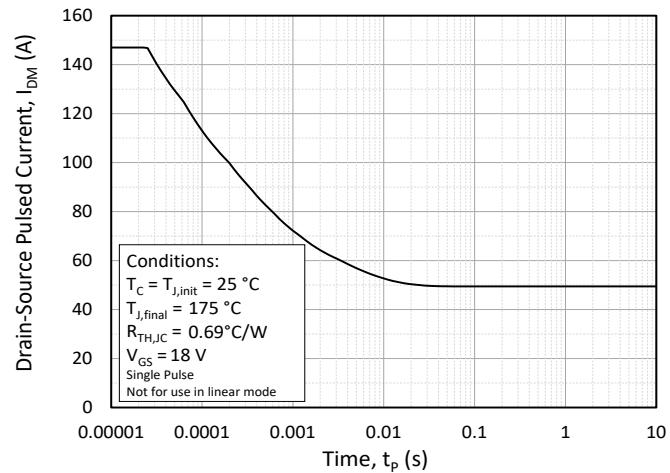


Figure 22. Safe Operating Area

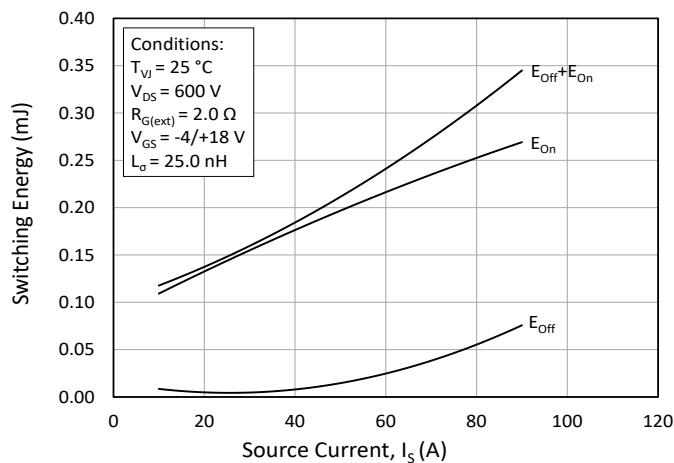


Figure 23. Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 600$ V)

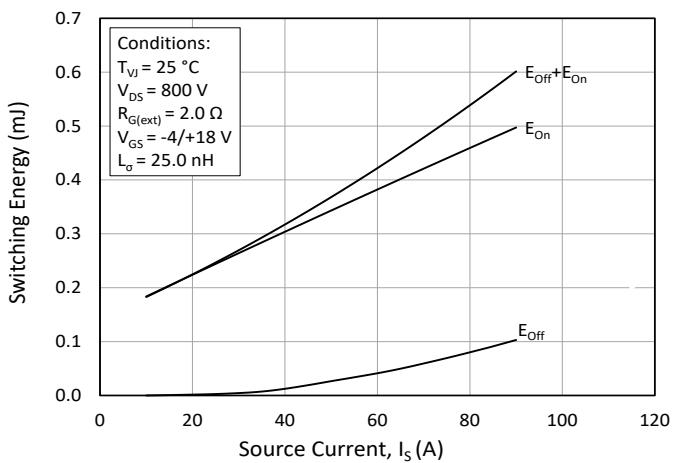


Figure 24. Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 800$ V)

Typical Performance

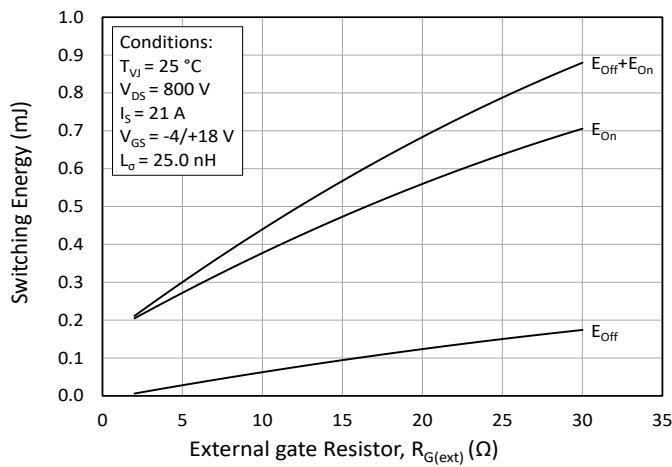
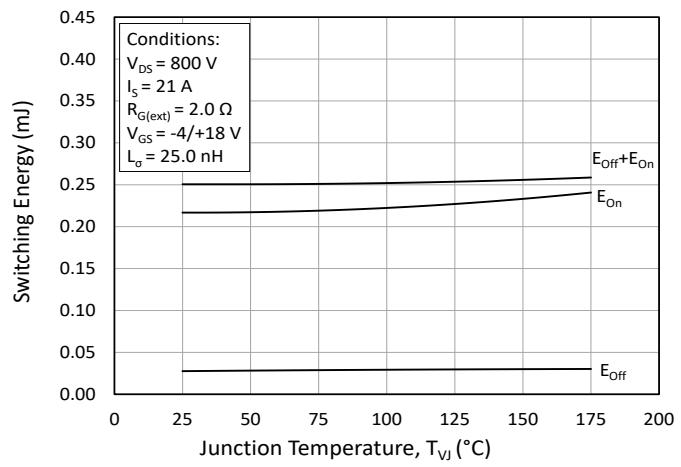
Figure 25. Clamped Inductive Switching Energy vs. $R_{G(\text{ext})}$ 

Figure 26. Clamped Inductive Switching Energy vs. Temperature

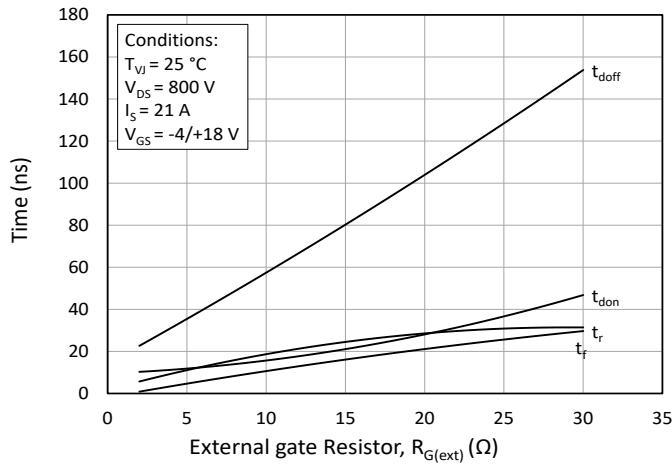
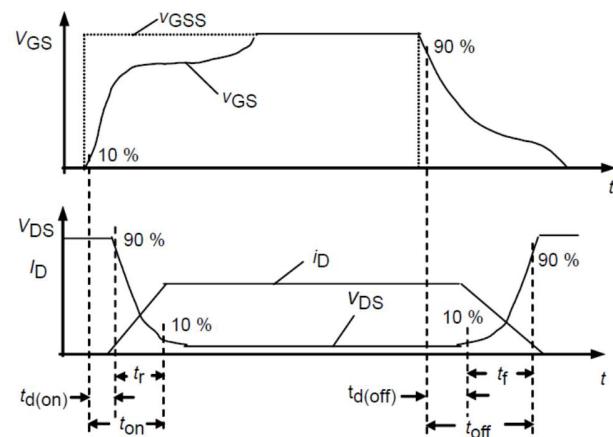
Figure 27. Switching Times vs. $R_{G(\text{ext})}$ 

Figure 28. Switching Times Definition

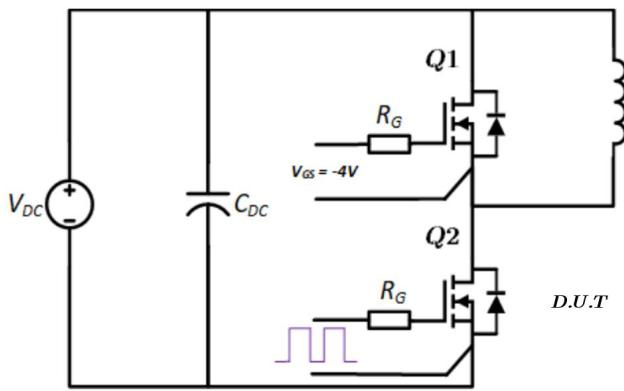


Figure 29. Clamped Inductive MOSFET Switching Waveform Test Circuit

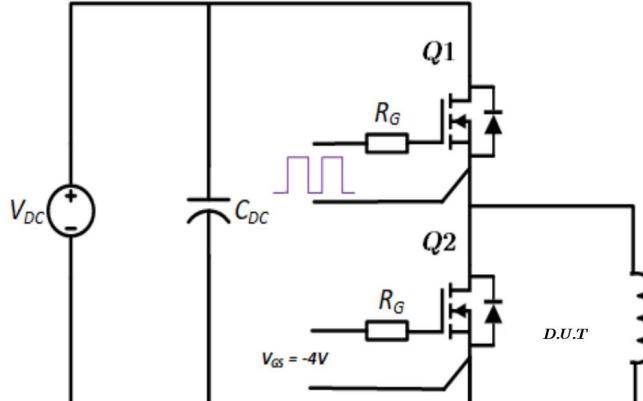
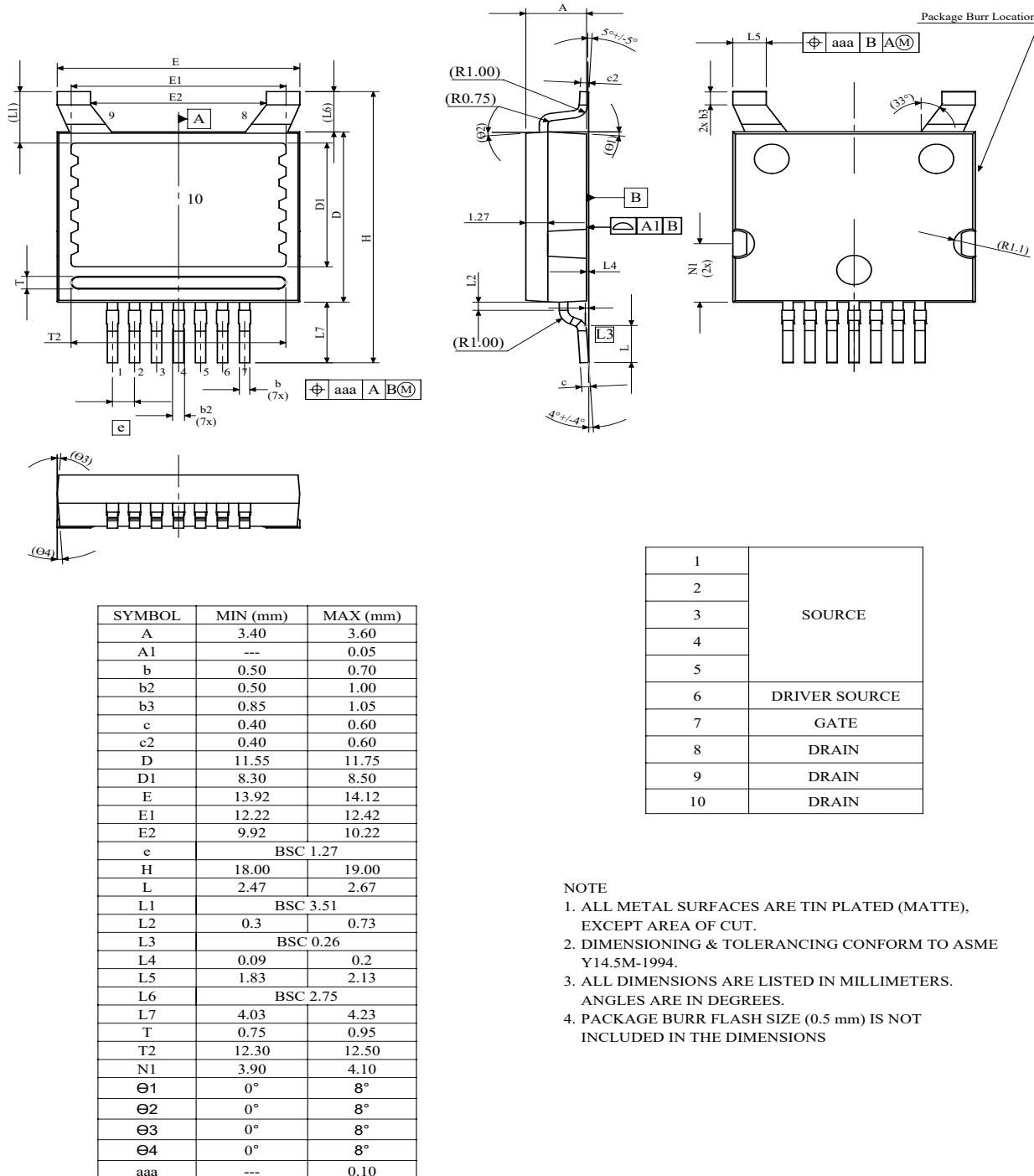


Figure 30. Clamped Inductive Body diode Switching Waveform Test Circuit

Package Dimensions



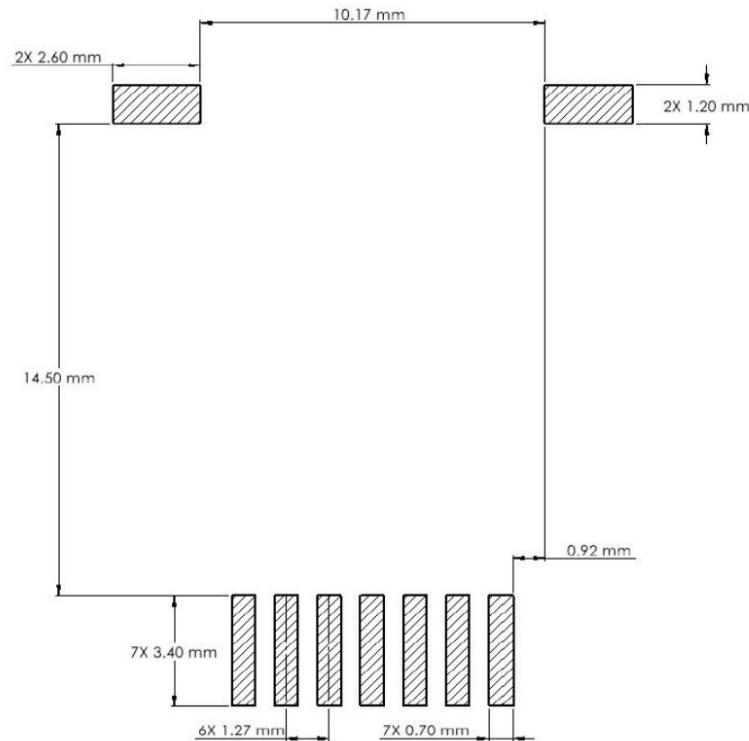
NOTE

1. ALL METAL SURFACES ARE TIN PLATED (MATTE), EXCEPT AREA OF CUT.
2. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
3. ALL DIMENSIONS ARE LISTED IN MILLIMETERS. ANGLES ARE IN DEGREES.
4. PACKAGE BURR FLASH SIZE (0.5 mm) IS NOT INCLUDED IN THE DIMENSIONS



Recommended Solder Pad Layout

All dimensions in mm





Revision history

Document Version	Date of release	Description of changes
1	October 2025	Initial release



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